Features and Benefits

- The control circuit and RGB chip are integrated in a 5050 components, to form an external control pixel.
- 12V power supply voltage can effectively reduce the working current of the whole pixel, reduce the voltage drop of the circuit board, and maximize the consistency of the mixed light when the pixel is transmitted over a long distance.
- Using the built-in signal reshaping circuit to achieve the signal waveform shaping, and no distortion of waveform of signal takes place.
- Each pixel of the three primary color can achieve 256 brightness display, completed 16777216 color full color display, and scan frequency is of 2KHz.
- Cascading port transmission signal by single line.
- Any two point the distance not more than 5m transmission signal without any increase circuit.
- When the refresh rate is 30fps, cascade number are not less than 1024 pixels.
- Send data at speeds of 800Kbps.
- The color of the light is highly consistent, cost-effective.

Applications

- Full-color module, LED full-color soft/hard light bar, LED guardrail tube.
- LED point light source, LED pixel screen,Special-shaped screen.

General description
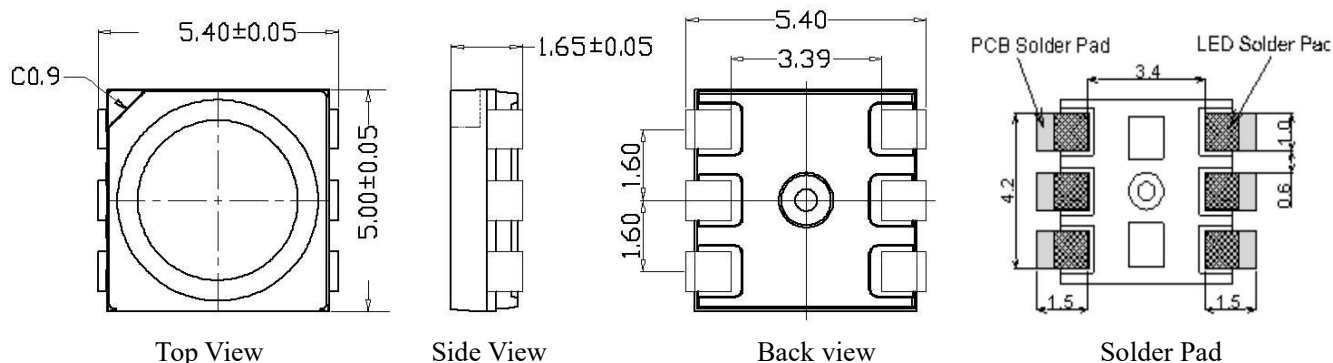
WS2815B is a intelligent control LED light source that the control circuit and RGB chip are integrated in a package of 5050 components.It internal include intelligent digital port data latch and signal reshaping amplification drive circuit.Also include a precision internal oscillator and a voltage programmable constant current control part, effectively ensuring the pixel point light color height consistent.Realize two-way signal transmission, in the case of damage to a single pixel, it does not affect the display of the overall color.

The data transfer protocol use single NZR communication mode. After the pixel power-on reset, the DIN port receive data from controller, the first pixel collect initial 24bit data then sent to the internal data latch, the other data which reshaping by the internal signal reshaping amplification circuit sent to the next cascade pixel through the DO port. After transmission for each pixel, the signal to reduce 24bit. pixel adopt auto reshaping transmit technology, making the pixel cascade number is not limited the signal transmission, only depend on the speed of signal transmission.
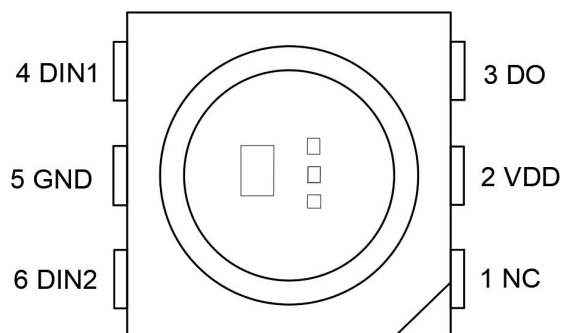
Refresh Frequency updates to **4KHz**, Low Frame Frequency and No Flicker appear in HD Video Camera,It is very suitable for high-speed mobile products.

RESET time>**280μs** , it won't cause wrong reset while interruption, it supports the lower frequency and inexpensive MCU.

http://www.world-semi.com

Mechanical Dimensions(Unit:mm)

| Top View | Side View | Back view | Solder Pad |

PIN Configuration

4 DIN1   3 DO
5 GND   2 VDD
6 DIN2   1 NC

PIN Function

NO.	Symbol	PIN	Function description
1	NC	NC	Suspended PIN
2	VDD	LED POWER SUPPLY	LED POWER SUPPLY, connect to "+12V"
3	DO	Data Output	Control data signal output
4	DIN1	Data-1 Input	Control data-1 signal input
5	GND	GROUND	Ground, data & power grounding
6	DIN2	Data-2 Input	Control data-2 signal input

Absolute Maximum Ratings (T_A=25°C, V_{SS}=0V, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Power supply voltage	V_{DD}	+9.5~+13.5	V
Power Consumption	P	0.1~0.18	W
Logical Input Voltage	V_I	-0.3~5.7	V
Working Temperature	Topt	-40~+65	°C
Storage Temperature	Tstg	-40~+85	°C

http://www.world-semi.com

Electrical Characteristics（T_A=25℃, V_{DD}=12V, V_{SS}=0V, unless otherwise specified）

Parameter	Symbol	Min	Tpy	Max	Unit	Conditions
Input current	I_I	——	——	±1	μA	V_I=V_{DD}/V_{SS}
High Voltage Input	V_{IH}	2.7	——	5.7	V	D_{IN}，SET
Low Voltage Input	V_{IL}	-0.3	——	1.5	V	D_{IN}，SET

Switching Characteristics（T_A=25℃, V_{DD}=12V, V_{SS}=0V, unless otherwise specified）

Parameter	Symbol	Min	Tpy	Max	Unit	Condition
Transmission delay time	t_{PLZ}	——	——	300	ns	CL=15pF, DIN→DOUT,RL=10KΩ
Fall time	t_{THZ}	——	——	120	μs	CL=300pF, OUTR/OUTG/OUTB
Input capacity	C_I	——	——	15	pF	——

LED Characteristics

Parameter	Symbol	Color	Quiescent Current＜2mA				Testing Condition DC=12V
			Mini	Typ	Max	Unit	Working current
Brightness	IV	Red	200	310	400	mcd	12mA
		Green	600	800	1000		
		Blue	150	190	300		
Wavelength	λd	Red	620	623	630	nm	12mA
		Green	510	520	520		
		Blue	465	471	475		

Data Transfer Time

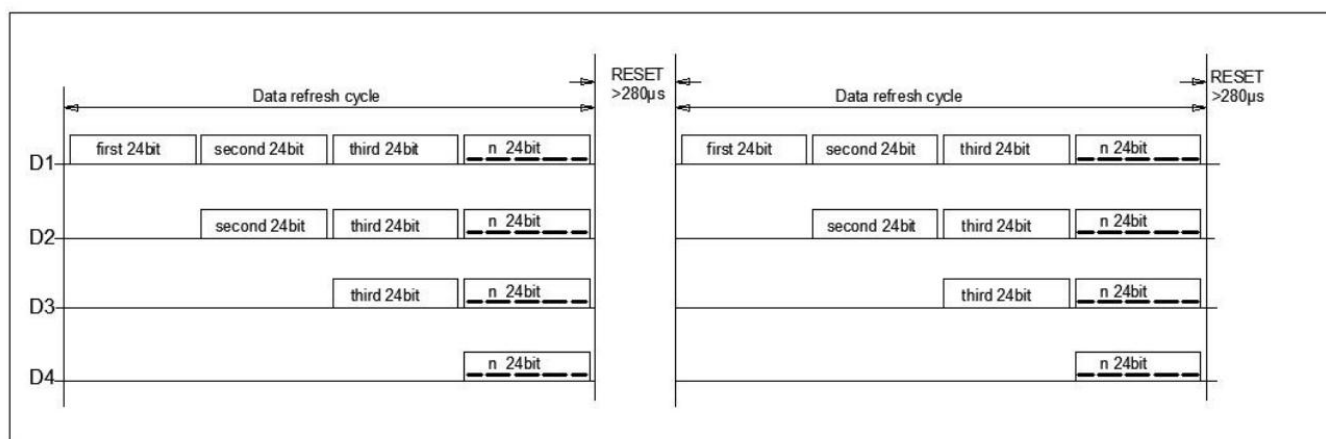| T0H	0 code, high voltage time	220ns~380ns
T1H	1 code, high voltage time	580ns~840ns
T0L	0 code, low voltage time	900ns~5000ns
T1L	1 code, low voltage time	600ns~5000ns
RES	Frame unit, low voltage time	>280μs
T_{DATA}	Data cycling time	≥1.25μs

http://www.world-semi.com

Timing Waveform

Sequence Chart
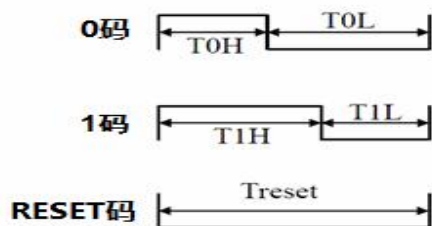
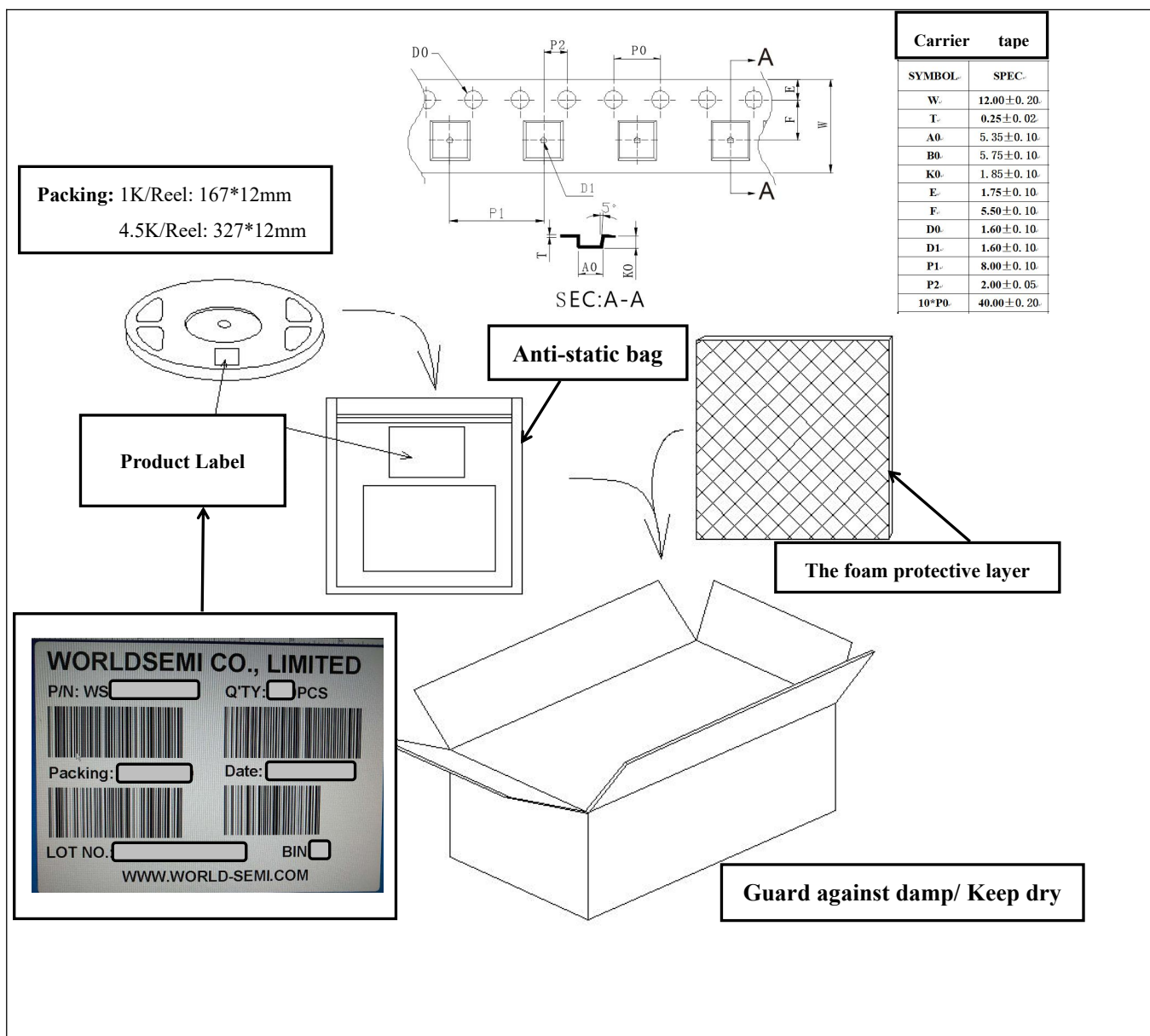**Cascade Method**
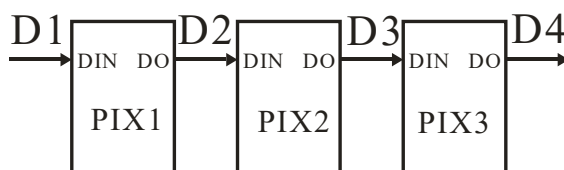
Data Transmission Method

Note: The data of D1 is send by MCU, and D2, D3, D4 through pixel internal reshaping amplification to transmit.

Composition of 24bit Data

G7	G6	G5	G4	G3	G2	G1	G0	R7	R6	R5	R4	R3	R2	R1	R0	B7	B6	B5	B4	B3	B2	B1	B0

Note: Data transmit in order of GRB, high bit data at first.

http://www.world-semi.com

Packing Standard

Packing: 1K/Reel: 167*12mm

4.5K/Reel: 327*12mm

Carrier	tape
SYMBOL	SPEC
W	12.00±0.20
T	0.25±0.02
A0	5.35±0.10
B0	5.75±0.10
K0	1.85±0.10
E	1.75±0.10
F	5.50±0.10
D0	1.60±0.10
D1	1.60±0.10
P1	8.00±0.10
P2	2.00±0.05
10*P0	40.00±0.20

SEC:A-A

Anti-static bag

Product Label

The foam protective layer

WORLDSEMI CO., LIMITED
P/N: WS□ Q'TY:□PCS
Packing:□ Date:□
LOT NO.□ BIN□
WWW.WORLD-SEMI.COM

Guard against damp/ Keep dry

http://www.world-semi.com

Top SMD LED Using Instructions

1. **Summary**

   To make the best use of WORLDSEMI's LED, please refer to the below precautions, they are of same usage method as other electronic components.

2. **Cautions**

2.1. Dust & Cleaning

   The surface of the LED is encapsulated with modified epoxy resin because it plays a very good role in protecting the optical performance and aging resistance. The modified epoxy resin is easy to stick with dust and must be kept clean. When there's a certain amount of dust on the surface of the LED, it won't affect brightness, but dust proof should be taken care of. Promoting the use of unsealed package in preference to others and the assembled LEDs should be placed in a clean container.

   Avoid using the organic solvents to clean the dust on the LED surface and it's necessary to confirm whether the cleaning fluid will dissolve the LED.

   Do not clean the LEDs by the ultrasonic. Some parameters affecting the LED performance must be evaluated if have no alternative but to the ultrasonic cleaning method, such as ultrasonic power, baking time and assembly conditions, etc.

2.2. Moisture-proof packaging

   TOP SMD LEDs are moisture sensitive components. LEDs are packaged in aluminum foil bag to prevent the from absorbing moisture during transport and storage. A desiccant is placed in the bags to absorb moisture. If the LED absorbs moisture, then it evaporates and expands when in reflow process, which may break the colloid from the bracket and damage the optical performance of LED. For this reason, moisture-proof packaging is to prevent the from absorbing moisture during transport and storage. The moisture resistance rating of WORLDSEMI's LED is: **LEVEL 5a.**

   Tabel I - IPC/JEDEC J-STD-020 Moisture/Reflow Sensitivity Classification

MSL Level	Workshop Life	
	Time	Conditions
LEVEL1	Unlimited	≤30℃/85%RH
LEVEL2	1 Year	≤30℃/60%RH
LEVEL2a	4 Weeks	≤30℃/60%RH
LEVEL3	168 Hours	≤30℃/60%RH
LEVEL4	72 Hours	≤30℃160%RH
LEVEL5	48 Hours	≤30℃/60%RH
LEVEL5a	**24 Hours**	**≤30℃/60%RH**
LEVEL6	Take-out and Use immediately	≤30℃/60%RH

http://www.world-semi.com

2.3 SMT Requirement：

2.3.1 It is recommended to unpack the LED before SMT and put the whole roll into the oven for dehumidification and drying (baking at 70 ~ 75 ℃ for ⩾ 24h);

2.3.2 The product is taken out of the oven to the completion of high-temperature soldering (including multiple high-temperature operations/operations such as reflow soldering, tin immersion, wave soldering, and heating maintenance), and the time period is controlled within 24 hours (under the conditions of T<30℃, RH<60%) ;

2.3.3SMT shall be completed as soon as possible for LED pastes on PCBA after printing solder paste, and it is recommended not to exceed 1H;

2.3.4 Bulk LEDs such as production surplus, machine throwing materials, and maintenance materials cannot be used directly if they are exposed to the air for a long time. It is recommended to dehumidify and dry before use. Whole roll baking: 70～75℃＊≧24H or bulk material baking: 120℃＊4H.
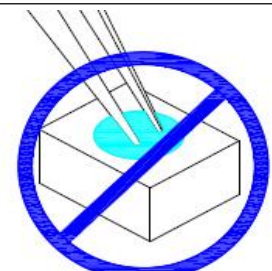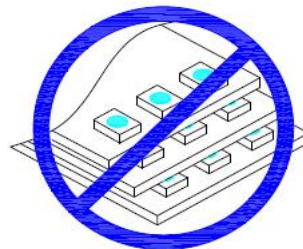
3. **SMT Reflow**

Refer to the parameters listed below, the experimental results prove that the TOP SMD LED meets the JEDEC J-STD-020C standards. As a general guideline, it is recommended to follow the SMT reflow temperature curve recommended by the solder paste manufacturer.

Temperature curve description	Range
30 ℃ ~ 150 ℃ preheating slope	1～4 ℃/s
30 ℃ ~ 150 ℃ preheating time	60～120 s
Constant temperature slope of 150 ℃ ~ 200 ℃	0～3 ℃/s
Constant temperature time of 150 ℃ ~ 200 ℃	60～120 s
LIQUID REGION temperature	217℃
Peak Temperature (Tp)	245℃
Reflow slope	0～3 ℃/s
Reflow time	45-90 s
cooling rate	-4～0 ℃/s
Room Temperature to Peak Holding Time	<6 min
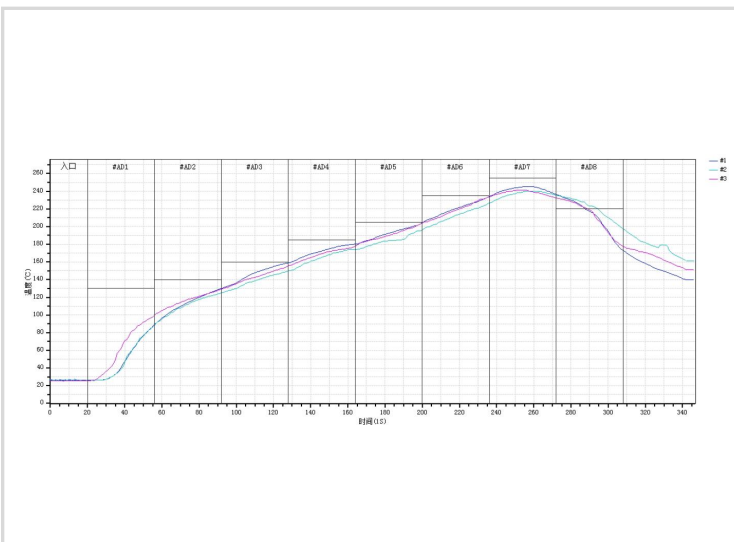
Remarks: All temperatures referred are measured on the surface of the package body.

http://www.world-semi.com

4. Assembly Precautions

1. Clip the LED from its side.	2. Neither directly touch the gel surface with the hand or sharp instrument, it may damage its internal circuit.	3. Not to be double stacked, it may damage its internal circuit.	4. Can not be stored in or applied in the acidic sites of PH<7.

Modify Record

Version №	Status Bar	Modify Content Summary	Date	Reviser	Approved
V1.0	N	New	20180820	Shen JinGuo	Yin HuaPing
V1.1	M	Brightness, Timing and SMT cautions	20190507	Shen JinGuo	Yin HuaPing
V1.2	M	Product description	20200519	Shen JinGuo	Yin HuaPing
V1.3	M	Product description	20210401	Dong Le	Yin HuaPing
V1.4	M	Using instructions	20220531	Yu XingHui	Yin HuaPing
V2.0	M	IC upgraded, parameters updated	20221020	Yu XingHui	Yin HuaPing
V2.1	M	Add power consumption	20221201	Yu XingHui	Yin HuaPing
V2.2	M	Timing sequence modified	20230315	Hu Jin	Yu XingHui

Remarks: Initial version: V1.0；Version number plus "0.1" after each revision;

Status bar: N--New, A--Add, M--Modify, D--Delete.

http://www.world-semi.com